

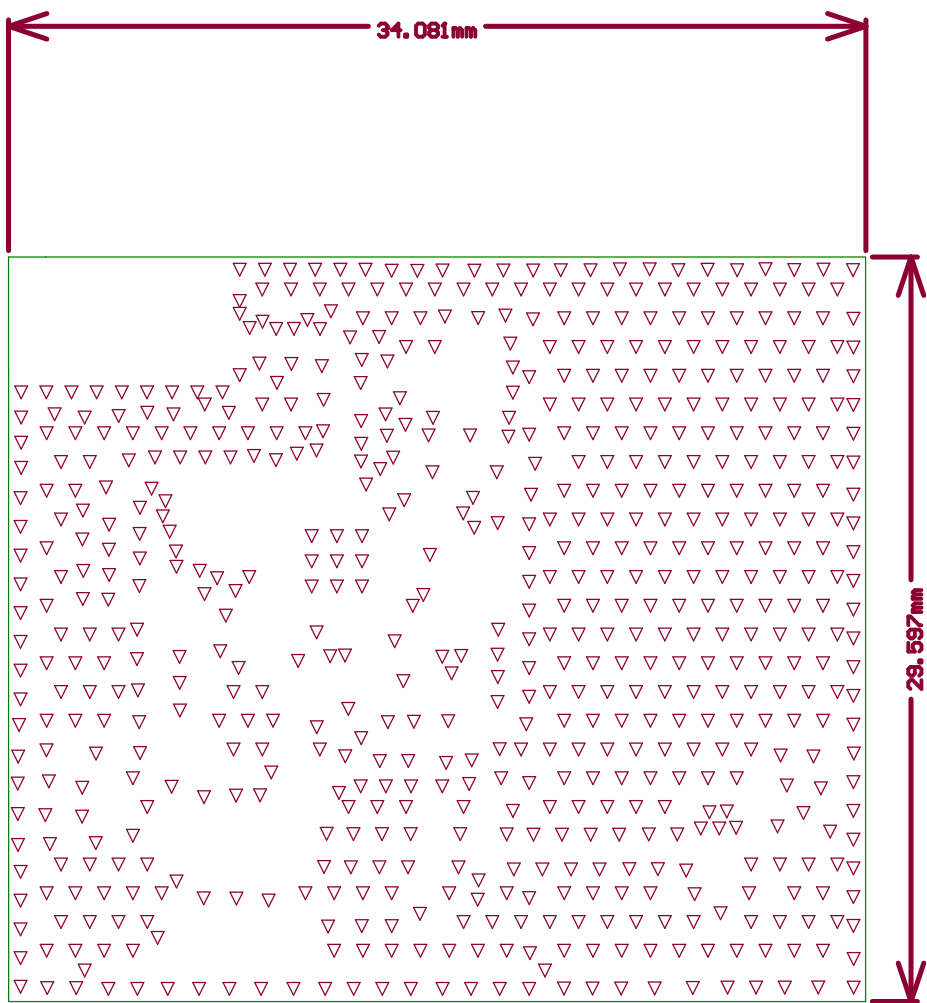
### Fabrication Notes:

1. All dimensions in inches. Tolerance =  $\pm 0.005$  unless noted otherwise.
2. All materials: laminates, resins, metallizations and soldermask to be compliant with RoHS and WEEE directives.
3. Use 370 HR FR-4 or similar grade glass epoxy.
4.  $T_g > 170$  degrees C, glass transition temperature.
5.  $TD > 350$  degrees C, thermal decomposition.
6. Minimum flammability rating UL94V-0, maximum dissipation factor 0.025.
7. Adjust prepreg for 0.032,  $\pm 0.003$  finished thickness measured over soldermask.
8. Copper thickness 0.0014, (1 oz).
9. Hole size tolerance =  $\pm 0.003$  unless noted otherwise.
10. Hole centers and pad centers to be concentric within 0.002.
11. Drill chart dimensions are finished hole sizes.
12. Finish - immersion gold over nickel. No exposed bare copper permitted.
13. Solder mask over bare copper, LPI clas 2 gen. industrial registration  $\pm 0.004$ .
14. No coverage on solder pads permitted.
15. Refer to soldermask gerbers for tenting of vias.
16. White silkscreen legend over red soldermask - both sides.
17. Manufacturer icons not permitted on the silkscreen top layer.
18. PCB serialization/panel placement ID on silkscreen bottom.
19. Full electrical test against IPC-356A netlist.

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer	Copper	1.40mil		
	Dielectric 1	FR-4	28.00mil	4.48	
2	Bottom Layer	Copper	1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				

**Total board thickness:** 31.60mil

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Pad Shape
▽	643	0.250mm	PTH	Round	Top Layer - Bottom Layer	Rounded
	643 Total					



# IoT Wireless Hardware Applications

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TITLE:  
EFR32xG22 Low Cost Reference Design

FILE NAME:  
EFR32xG22\_LC\_REF\_DES\_RevA01.PcbDoc

Board NO.:  
EFR32xG22\_LCRD

REV:  
A01

Layer: Drill Drawing

DATE:  
9/25/2020

1		2		3		4	

	1	2	3	4	
					A
					B
C	<div></div>				C
D	IoT Wireless Hardware Applications		<div> <b>SILICON LABS</b> 343 Congress St 4th Floor Boston, MA 02210 www.silabs.com 617-951-0200</div>		D
	1	2	3	4	

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		FILE NAME: EFR32xG22_LC_REF_DES_RevA01.PcbDoc	
		Board NO.: EFR32xG22_LCRD	REV: A01
		Layer: Top Paste	DATE: 9/25/2020

	1	2	3	4	A
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C	<div></div>				C
D	IoT Wireless Hardware Applications		<div><div>SILICON LABS 343 Congress St 4th Floor Boston, MA 02210 <a href="#">www.silabs.com</a> 617-951-0200</div></div>		D
				<div>TITLE: EFR32xG22 Low Cost Reference Design</div> <div>FILE NAME: EFR32xG22_LC_REF_DES_RevA01.PcbDoc</div> <div>Board NO.: EFR32xG22_LCRD</div> <div>Layer: Top Solder</div>	<div>REV: A01</div> <div>DATE: 9/25/2020</div>
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					A							
					B							
C	<div></div>				C							
D	IoT Wireless Hardware Applications		<div><p><b>SILICON LABS</b> 343 Congress St 4th Floor Boston, MA 02210 www.silabs.com 617-951-0200</p></div>		D							
				<table><tr><td colspan="2">TITLE: EFR32xG22 Low Cost Reference Design</td></tr><tr><td colspan="2">FILE NAME: EFR32xG22_LC_REF_DES_RevA01.PcbDoc</td></tr><tr><td>Board NO.: EFR32xG22_LCRD</td><td>REV: A01</td></tr><tr><td>Layer: Top Layer</td><td>DATE: 9/25/2020</td></tr></table>	TITLE: EFR32xG22 Low Cost Reference Design		FILE NAME: EFR32xG22_LC_REF_DES_RevA01.PcbDoc		Board NO.: EFR32xG22_LCRD	REV: A01	Layer: Top Layer	DATE: 9/25/2020
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Board NO.: EFR32xG22_LCRD	REV: A01											
Layer: Top Layer	DATE: 9/25/2020											
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TITLE:  
EFR32xG22 Low Cost Reference Design

FILE NAME:  
EFR32xG22\_LC\_REF\_DES\_RevA01.PcbDoc

Board NO.: EFR32xG22_LCRD	REV: A01
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Layer:	DATE:
Bottom Solder	9/25/2020

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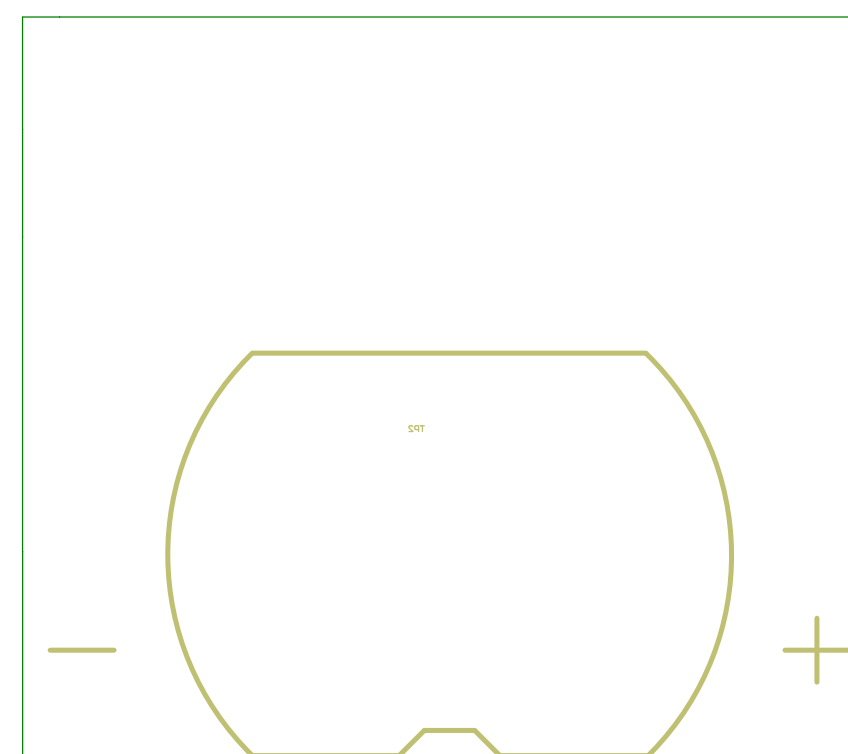
4

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C

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FILE NAME:  
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Board NO.:  
EFR32xG22\_LCRD

REV:  
A01

Layer: Bottom Overlay

DATE:  
9/25/2020

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